BTA204W series B and C

GENERAL DESCRIPTION

Passivated high commutation triacs in a plastic envelope suitable for surface mounting intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature without the aid of a snubber.

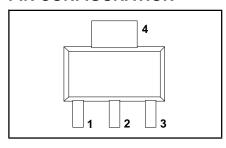
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{DRM}	BTA204W- BTA204W- Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state	500 1	600B 600C 600	800B 800C 800	V A A
ITSM	current	10	10	10	

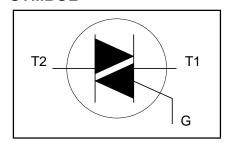
PINNING - SOT223

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
tab	main terminal 2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V_{DRM}	Repetitive peak off-state voltages			-500 500 ¹	-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-		1		A
I _{TSM}	Non-repetitive peak on-state current	$T_{sp} \le 108 ^{\circ}\text{C}$ full sine wave; $T_{j} = 25 ^{\circ}\text{C}$ prior to surge $t = 20 \text{ms}$,		10		A
12.	12	t = 16.7 ms	-		11		A A ² s
l ² t dl _T /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering	t = 10 ms $I_{TM} = 1.5 \text{ A};$ $I_{G} = 0.2 \text{ A};$ $dI_{G}/dt = 0.2 \text{ A}/\mu\text{s}$	-	0.5 100		A's A/μs	
${f I}_{GM} {f V}_{GM}$	Peak gate current	a.g, at 0.2 / 1/20	-		2		A
$\begin{array}{c} V_{GM} \\ P_{GM} \\ P_{G(AV)} \end{array}$	Peak gate voltage Peak gate power Average gate power	over any 20 ms	-		2 5 5 0.5		W W
T_{stg}^{stg}	Storage temperature Operating junction temperature	-40 150 - 125			ပို		

December 1998 1 Rev 1.000

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 A/µs.

BTA204W series B and C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-sp}	Thermal resistance junction to solder point	full or half cycle	-	-	15	K/W
R _{th j-a}	Thermal resistance	pcb mounted; minimum footprint pcb mounted; pad area as in fig:2	-	156 70	- -	K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MA	۱X.	UNIT
		BTA204W-			В	С	
I _{GT}	Gate trigger current ²	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$					
		T2+ G+	-	-	50	35	mA
		T2+ G-	-	-	50	35	mA
		T2- G-	-	-	50	35	mA
I _L	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$					
_		T2+ G+	-	-	30	20	mA
		T2+ G-	-	-	45	30	mA
		T2- G-	-	-	30	20	mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	-	30	20	mA
V_T	On-state voltage	$I_T = 2 A$	-	1.2	1.	.5	V
V _{GT}	Gate trigger voltage	$V_D = 12 \text{ V}$: $I_T = 0.1 \text{ A}$	-	0.7	1.	.5	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	0.25	0.4		-	V
l _D	Off-state leakage current	$T_{j} = 125 ^{\circ}\text{C}$ $V_{D} = V_{DRM(max)}, T_{j} = 125 ^{\circ}\text{C}$	_	0.1	0.	.5	mA

DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		UNIT
		BTA204W-	В	C		
dV _D /dt	Critical rate of rise of off-state voltage	V _{DM} = 67% V _{DRM(max)} ; T _j = 125 °C; exponential waveform; gate open circuit	1000	1000	-	V/µs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 1 \text{ A}; $ $dV_{com}/dt = 20 \text{ V}/\mu\text{s}; \text{ gate open circuit}$	6	3	-	A/ms
t _{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	-	2	μs

² Device does not trigger in the T2-, G+ quadrant.

BTA204W series B and C

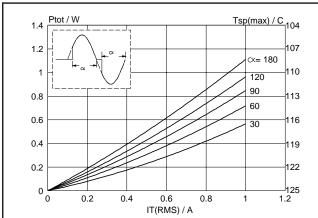


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

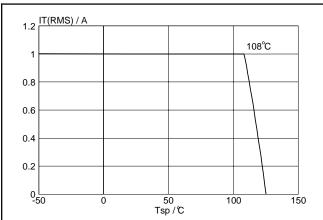


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus solder point temperature T_{sp} .

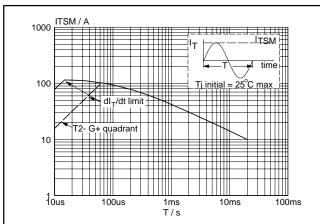


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

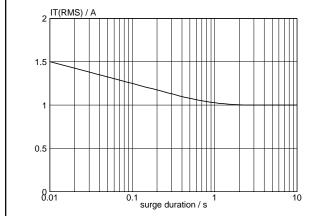


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{sp} \le 108$ °C.

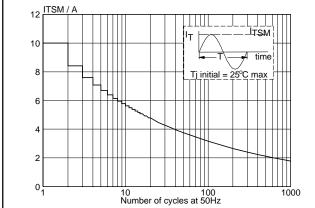


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

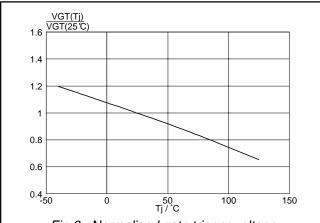
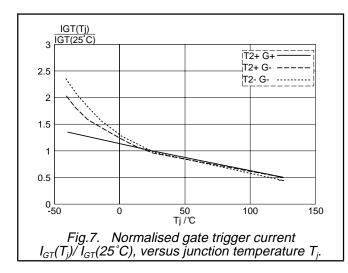
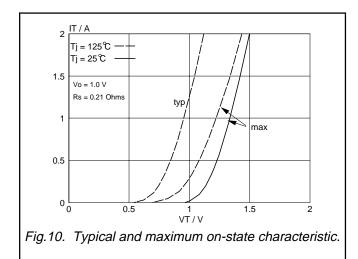
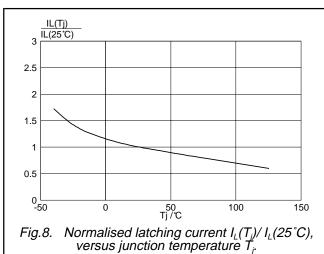


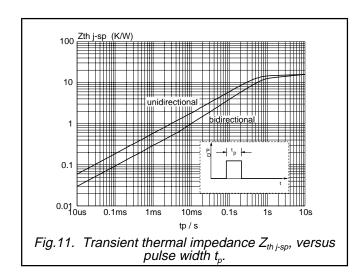
Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25\,^{\circ}C)$, versus junction temperature T_j .

BTA204W series B and C









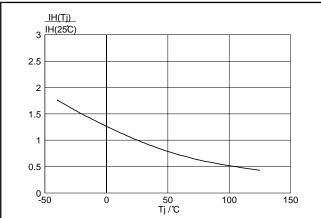
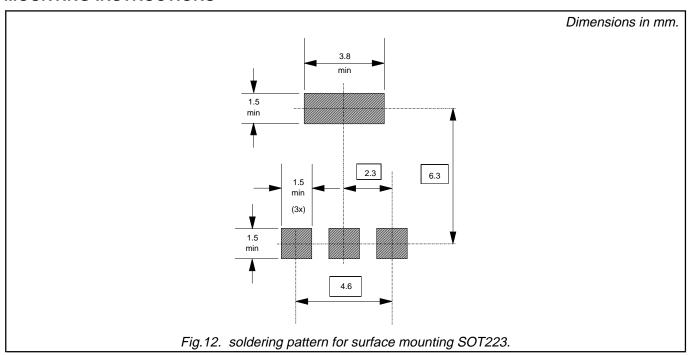
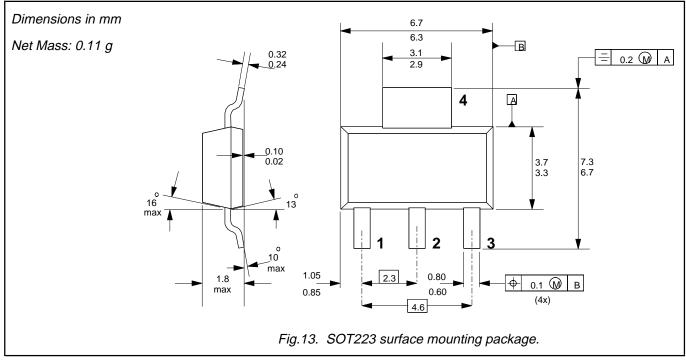


Fig.9. Normalised holding current $I_H(T_i)/I_H(25\,^{\circ}C)$, versus junction temperature T_i .

MOUNTING INSTRUCTIONS



MECHANICAL DATA



Notes

- 1. For further information, refer to Philips publication SC18 " SMD Footprint Design and Soldering Guidelines". Order code: 9397 750 00505. 2. Epoxy meets UL94 V0 at 1/8".

BTA204W series B and C

Product specification

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Product specification	This data sheet contains final product specifications.				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 1998

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.